



Product Change Notification / DSNO-10JHUT663

Date:

14-Jun-2024

Product Category:

8-Bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 7041 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATTINY16x, ATTINY204, ATTINY214, ATTINY322, ATTINY4x, ATTINY8x, ABR16EB14, PIC16F131, PIC16F152, PIC16F171, PIC16F180 and PIC16F181 device families available in 14L SOIC (.150in) package at MTAI assembly site.

Affected CPNs:

[DSNO-10JHUT663_Affected_CPN_06142024.pdf](#)

[DSNO-10JHUT663_Affected_CPN_06142024.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATTINY16x, ATTINY204, ATTINY214, ATTINY322, ATTINY4x, ATTINY8x, ABR16EB14, PIC16F131, PIC16F152, PIC16F171, PIC16F180 and PIC16F181 device families available in 14L SOIC (.150in) package at MTAI assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	
Wire Material	Au	Au	CuPdAu
Die Attach Material	8390A	8390A	
Molding Compound Material	G600V	G600V	
Lead-Frame Material	A194	A194	

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity and on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) as an additional bond wire material at MTAI assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:July 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	June 2024					July 2024				
Workweek	22	23	24	25	26	27	28	29	30	31
Initial PCN Issue Date			x							
Qual Report Availability									x	
Final PCN Issue Date									x	

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: June 14, 2024: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_DSNO-10JHUT663_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

ATTINY804-SSF
ATTINY804-SSFR
ATTINY804-SSN
ATTINY804-SSNR
PIC16F15224-E/SL
PIC16F15224-I/SL
PIC16F15224T-I/SL
PIC16F15224T-E/SL
PIC16F18124-I/SL
PIC16F18124T-I/SL
PIC16F18124-E/SL
PIC16F17124-I/SL
PIC16F17124T-I/SL
PIC16F17124-E/SL
PIC16F13124-E/SL
PIC16F13124-I/SL
PIC16F13124T-I/SL
PIC16F18024-E/SL
PIC16F18024-I/SL
PIC16F18024T-I/SL
ATTINY404-SSN
ATTINY404-SSNR
PIC16F15223-E/SL
PIC16F15223-I/SL
PIC16F15223T-I/SL
PIC16F13123-E/SL
PIC16F13123-I/SL
PIC16F13123T-I/SL
PIC16F18023-E/SL
PIC16F18023-I/SL
PIC16F18023T-I/SL
ATTINY204-SSF
ATTINY204-SSFR
ATTINY204-SSN
ATTINY204-SSNR
PIC16F17126-I/SL
PIC16F17126T-I/SL
PIC16F17126-E/SL
PIC16F18126-I/SL
PIC16F18126T-I/SL
PIC16F18126-E/SL
PIC16F18026-E/SL
PIC16F18026-I/SL
PIC16F18026T-I/SL
ATTINY814-SSFR
ATTINY814-SSF

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ATTINY824-SSU
ATTINY824-SSUR
ATTINY824-SSF
ATTINY824-SSFR
ATTINY424-SSU
ATTINY424-SSUR
ATTINY424-SSF
ATTINY424-SSFR
ATTINY3224-SSU
ATTINY3224-SSUR
ATTINY3224-SSF
ATTINY3224-SSFR
ATTINY1624-SSU
ATTINY1624-SSUR
ATTINY1624-SSF
ATTINY1624-SSFR
ATTINY1604-SSF
ATTINY1604-SSFR
ATTINY1604-SSN
ATTINY1604-SSNR
AVR16EB14-E/SL
AVR16EB14-I/SL
AVR16EB14T-I/SL
AVR16EB14T-E/SL
PIC16F18125-I/SL
PIC16F18125T-I/SL
PIC16F18125-E/SL
PIC16F17125-I/SL
PIC16F17125T-I/SL
PIC16F17125-E/SL
PIC16F15225-E/SL
PIC16F15225-I/SL
PIC16F15225T-I/SL
PIC16F18025-E/SL
PIC16F18025-I/SL
PIC16F18025T-I/SL
PIC16F13125-E/SL
PIC16F13125-I/SL
PIC16F13125T-I/SL
ATTINY214-SSF
ATTINY404-SSF
ATTINY414-SSF
ATTINY1614-SSF
ATTINY414-SSFR
ATTINY404-SSFR
ATTINY214-SSFR
ATTINY1614-SSFR
ATTINY814-SSN

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ATTINY414-SSN

ATTINY814-SSNR

ATTINY814-SSNRA1

ATTINY214-SSNR

ATTINY414-SSNR

ATTINY1614-SSNR